IN THE CLAIMS

Please amend the claims as follows:

36. (Currently Amended) A device [for an edge bead,] comprising:

a dispenser configured to release a chemical toward [said] an edge bead; and

a splash controller around said dispenser, physically unattached from [said] the edge

bead, and configured to draw [said] the chemical toward said splash controller,

wherein said splash controller is configured to generate a gas pressure around [said]

the edge bead that is lower than an ambient gas pressure, and wherein said splash

controller is configured to physically intercept [said] the chemical.

37. (Currently Amended) The device in claim 36, wherein [said] the splash controller is around

[said] the edge bead.

38. (New)   The device of claim 36, wherein the splash controller completely surrounds said

dispenser.

39. (New)   The device of claim 36, wherein the dispenser has a diameter smaller than a

diameter of the splash controller.

40. (New)   The device of claim 36, wherein said dispenser is configured to release a chemical

on a first side of a wafer and a second side of the wafer toward an edge bead, wherein the splash

controller completely surrounds said dispenser.

41. (New)   A device comprising:

a dispenser configured to release a chemical toward an edge bead on a semiconductor

substrate; and

a splash controller including a vacuum port, wherein the vacuum port completely surrounds

the dispenser, wherein the vacuum port is configured to generate a gas pressure around the edge

bead and the dispenser, the generated gas pressure being sufficiently lower than an ambient gas

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111
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Filing Date: August 31, 2000
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pressure to draw the chemical toward the splash controller, wherein the dispenser has a smaller diameter than the vacuum port, and wherein the splash controller is configured to physically intercept the chemical.